

IDEAS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV. ECN. NO. APPD.

REV.	ECN. NO.	APPD.
A	HC040065	W.L.C
B	BC04723034	W.L.C
C	BC05708516	JOHN CHOW
D	BC07706462	JOHN CHOW
E	BC-07-7033290	JOHN CHOW
F	BC-08-7088795	L.C.WU

NOTES:

- 1.DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994.
- 2.MATERIAL:
HOUSING: LCP, COLOR: BLACK. UL 94V-0.
CONTACT: PHOSPHOR BRONZE.
PLATING: 2.54um(100u") MIN. NICKEL-PLATING OVER ALL.
0.76um(30u") OR .38um(15u")MIN. GOLD-PLATING ON CONTACT AREA.
2.54um(100u") MIN. ① TIN-LEAD(90/10) ② SATIN TIN PLATING ON SOLDER AREA.
- 3.RECOMMENDED THICKNESS OF MATING PCB IS 1.00±0.10mm.
- 4.RECOMMENDED OPERATION TEMPERATURE TO BE -55°C TO 85°C,
NON-OPERATING TEMPERATURE TO BE -55°C TO 105°C.
- 5.THE PEAK OF SOLDERING TEMPERATURE TO BE 260±5°C FOR LEAD FREE PRODUCT (3S10202*-011-7F),
TO BE 245±5°C FOR TIN/LEAD PRODUCT (3S10202*-011).

PART LIST

3S10202*-011-**-**

LEAD FREE CODE
NONE:TIN/LEAD
F:LEAD FREE

PACKAGE:
7: TAPE & REEL

CONTACT AREA PLATING:
3: 30u" MIN. GOLD PLATING
7: 15u" MIN. GOLD PLATING

3S10202*-011-7F ② SATIN TIN ROHS 6 COMPLIANCE

3S10202*-011 ① TIN/LEAD ROHS 5 COMPLIANCE

P/N FINISH REMARK

X.±	X.'±1"	UNITS mm	NAME (INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.D.C.
.X± 0.20	.X'±	MAT'L	SFP CONNECTOR	
.XX± 0.15	.XX'±	△	PART NO.(INTENDED USE) 3S10202*-011 3S10202*-011-7F	TITLE: CUSTOMER DRAWING
.XXX±	.XXX'±	FINISH	APPD: L.C.WU 8/11'08	DWG NO.: 323-0000-1055
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.			Q'TY	CHKD:PIER HSU 8/11'08 DR: TIM XUE 8/11'08

SCALE: 1/2 F

REV.	ECN. NO.	APPD.
A	HC040065	W.L.C
B	BC04723034	W.L.C
C	BC05708516	JOHN CHOW
D	BC07706462	JOHN CHOW
E	BC-07-7033290	JOHN CHOW
F	BC-08-7088795	L.C.WU

NOTES:

1.DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994.

2. MATERIAL:

HOUSING: LCP, COLOR: BLACK. UL 94V-0.

CONTACT: PHOSPHOR BRONZE.

PLATING: 2.54um(100u") MIN. NICKEL-PLATING OVER ALL.

0.76um(30u") OR .38um(15u")MIN. GOLD-PLATING ON CONTACT AREA.

2.54um(100u") MIN. ① TIN-LEAD(90/10) ② SATIN TIN PLATING ON SOLDER AREA.

3. RECOMMENDED THICKNESS OF MATING PCB IS $1.00 \pm 0.10 \text{ mm}$.

4. RECOMMENDED OPERATION TEMPERATURE TO BE -55°C TO 85°C ,

NON-OPERATING TEMPERATUE TO BE -55°C TO 105°C.

5. THE PEAK OF SOLDERING TEMPERATURE TO BE 260±5°C FOR LEAD FREE PRODUCT (3S10202*-011-7F), TO BE 245±5°C FOR TIN/LEAD PRODUCT (3S10202*-011).

PART LIST

3S10202*-011-*

— LEAD FREE CODE
NONE:TIN/LEAD
F:LEAD FREE

— PACKAGE:
7: TAPE & REEL

CONTACT AREA PLATING: _____
3: 30u" MIN. GOLD PLATING
7: 15u" MIN. GOLD PLATING

3S10202*-011-7F	② SATIN TIN	ROHS 6 COMPLIANCE
3S10202*-011	① TIN/LEAD	ROHS 5 COMPLIANCE
P/N	FINISH	REMARK

X. ±		X. ± 1 *	UNITS mm	NAME (INTENDED USE)		FOXCONN	
.X ± 0.20		.X *	MAT'L	SFP		HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.	
.XX ± 0.15	.XX *	FINISH ⚠	Q'TY	PART NO. (INTENDED USE)		TITLE:	
.XXX ±	.XXX *			3S10202-011 3S10202*-011-7F		CUSTOMER DRAWING	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.				APPD: L.C.WU 8/11/08		DWG NO.:	
				CHKD: PIER HSU 8/11/08		323-0000-1055	
				DR: TIM XUE 8/11/08		 SCALE: 1/2" = 1"	

